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# Foreword

## Thermal and Mechanical Simulation and Experiments in Microelectronics and Microsystems

This special issue includes selected papers presented at the *International Conference of Thermal and Mechanical Simulation and Experiments in Microelectronics and Microsystems (EuroSimE)*, Paris, May 2001. The annual EuroSimE conference was initiated in 2000, as the only international conference focusing on mechanical, thermal and thermo-mechanical simulation and experiments in microelectronics and microsystems, with financial co-sponsorship from the EC, and technical co-sponsorship of IEEE-CPMT, in order to meet the growing needs and challenges in this rapidly progressing field.

The selected articles cover a broad field of technical subjects including mechanical simulation (both static and dynamic); thermo-mechanical simulation; thermal management; material characterization and modeling; thin-film mechanics; failure criteria and damage-modeling; continuum and micromechanics in microelectronics; interface strengths; experiments for model verification; product/process optimization; simulation-based optimization; virtual thermo-mechanical prototyping in product/process design and qualification; multi-physics simulation; advanced numerical and analytical simulation methodologies and tools.

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